产品承认书

SPECIFICATION FOR APPROVAL

CUSTOMER：	
CUSTOMER P/N：	
CND-TEK P/N. :	G8801D
DESCRIPTION：	1000 BASE-T MAGNETICS MODULES
REF NO:	QTC-001
REV/NO:	V1.02
DATE:	2015/03/02

ATTACHMENT：

■ SPECIFICATION

■ SAMPLE　Q'TY OF SAMPLES　　PCS

	√	CUSTOMER'S SIGNATURE	REMARK
FULL APPROVED			
CONDITIONAL APPROVED			
REJECTED			

G8801D

1000 BASE-T MAGNETICS MODULES

V1.0.2
Feb 2, 2015

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1. FEATURES:

1.1 Designed for long haul Gigabit Ethernet 1000 Base-T, full duplex applications.

1.2 Supports four pairs of category 5 UTP cable.

1.3 Cable interface for isolation and low common mode emissions

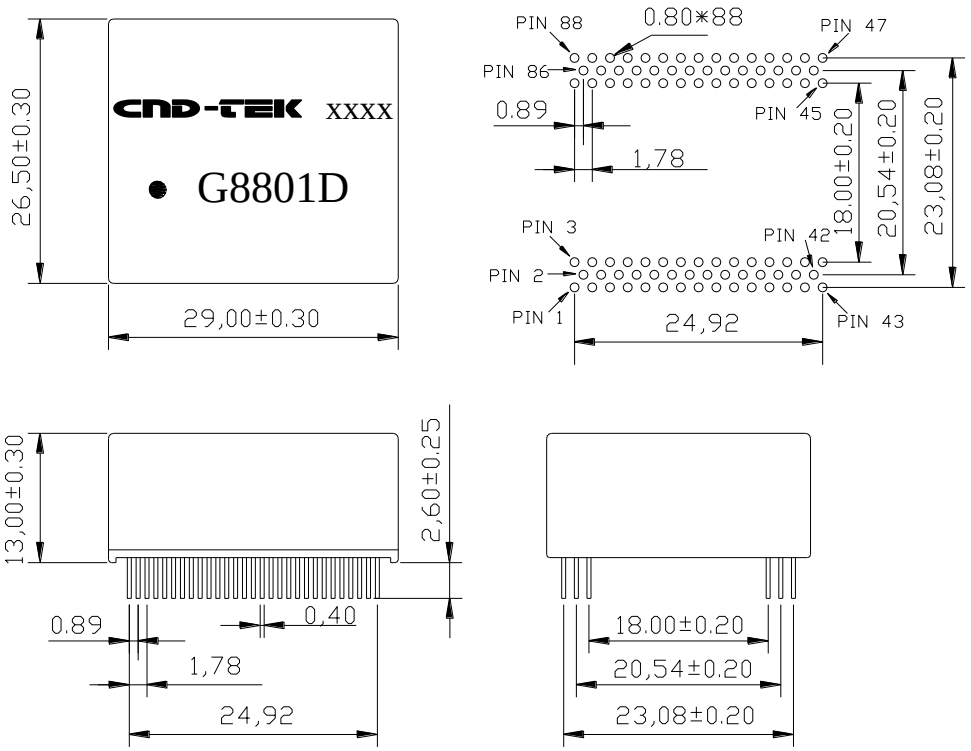
1.4 Compliant with IEEE 802.3ab standard for 1000 Base-T

1.5 Designed to support 1:1 Turns Ratio Transceivers.

1.6 Operating Temperature range: 0℃ TO +70℃

1.7 Storage temperature range: -25℃ TO +125℃

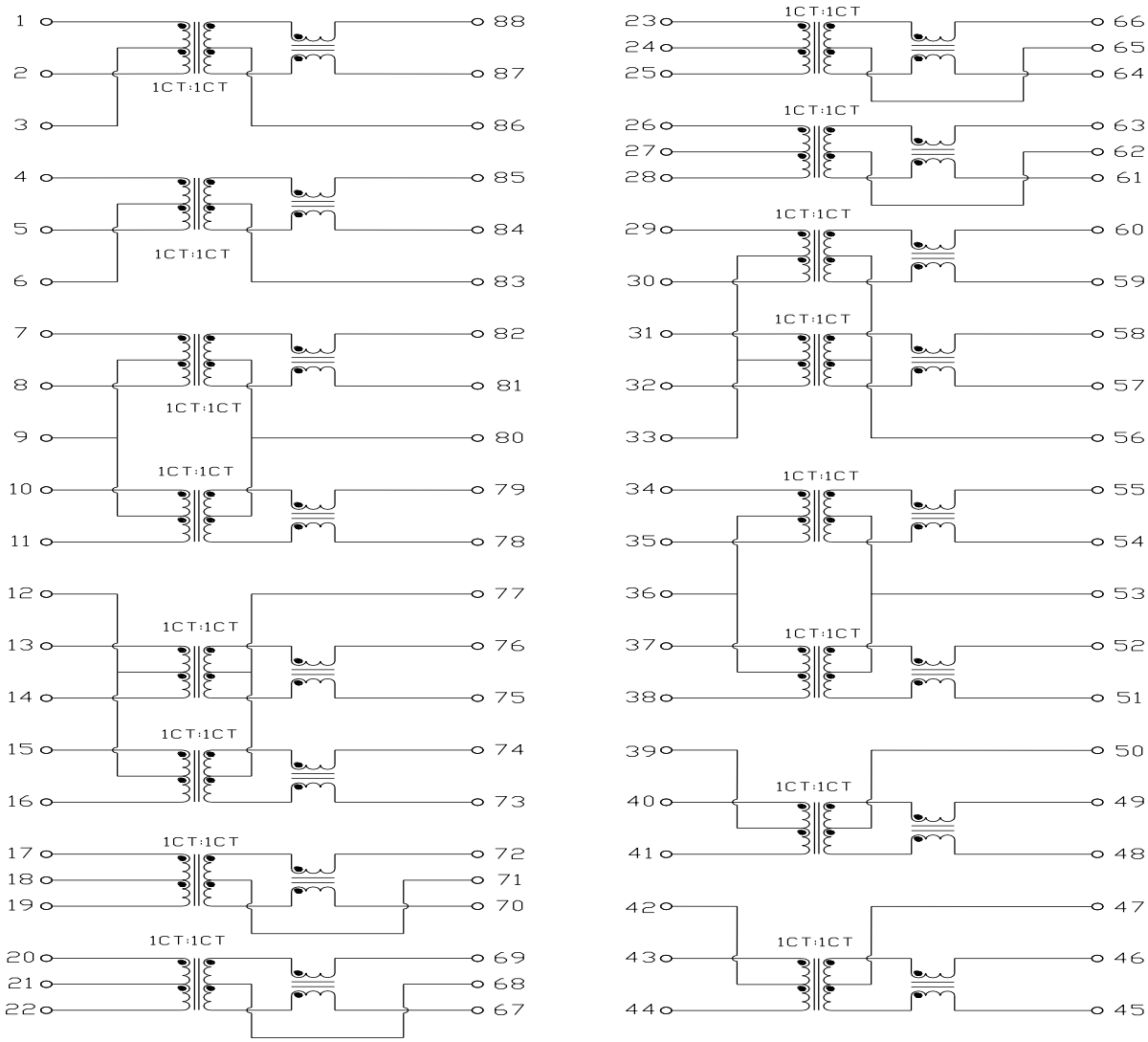
2. DIMENSIONS & MARKING



Note：1、Dimension：mm

2、Unless otherwise specified,all tolerances are：±0.05mm

3. SCHEMATICS:



4.ELECTRICAL SPECIFICATIONS @25℃

4.1 OCL : 350 μH Min. @ 100 KHz, 100mV with 8mA DC Bias

4.2 Leakage Inductance: 0.5 μH Max. @ 100KHz, 0.2V

4.3 Cw/w: 35 pF Max. @ 100KHz, 0.2V

4.4 DCR: 1.40Ω Max.

4.5 Turns Ratio(±5%): 1CT:1CT(TX), 1CT:1CT(RX)

4.6 Polarity 1-72, 3-70, 5-68, 7-66 In-Phase

4.7 Insertion Loss -1.2 dB Max. (TX & RX)@ 1~100 MHz

4.8 Return Loss: -16 dB Min @ 0.5-40MHz

4.9 Cross Talk: -50 dB Min.@ 1~10 MHz

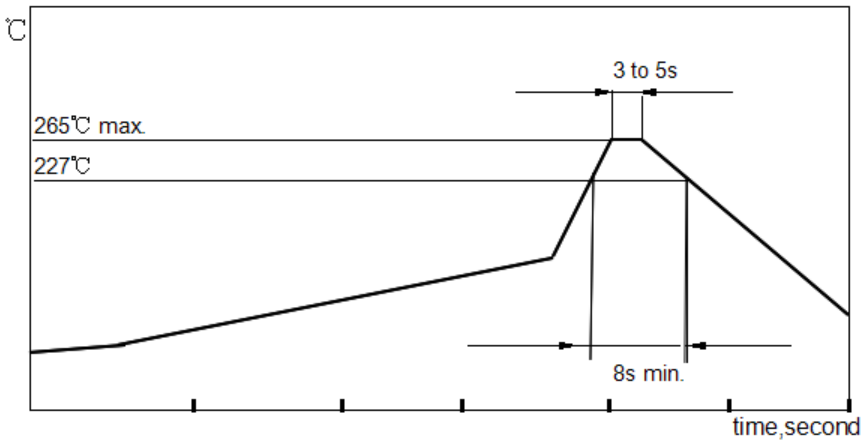
-55+22*log(f/10) dB Min.@ 10~100 MHz

4.10 Common Mode Rejection : -50 dB Min.@ 2 MHz

-15+20*log(f/200) dB Min.@ 30~200 MHz

4.11 Isolation HI-POT: 1500Vrms 1mA 1Second

5. Recommended Lead Free IR Reflow Soldering Curve：



Item	Soldertechnique simulation	Temperature (℃)	Time(s)	Temperature ramp/immersion and emersion rate
1	Solder iron	350±10 (solder irno temp)	4~5	
2	Vapor phase reflow	215±5 (vapor temp)	60±5	
3	IR/convection reflow	255±5 (component temp)	30±5	1℃/s~4℃/s time above 183℃ 90s~120s

Note：The curve includes recommended value only, please adjust your equipment to make sure the solder process.Details please refers to the standard J-STD-020.

6. Reliability Test Criteria：

6.1 Terminal strength: Pull test withstand 9.8N 60+/-0.5S no looseness or movement.

6.2 Solderbility: Dipped in 245℃+/-5℃ molten solder for 3+/-0.5 seconds,95% min shall be smooth any and bright.

6.3 Resistance to soldering heat : Convection reflow condition setting: peak temperature at 260℃+0/-5℃ above 217℃ for 90-180 seconds, ramp-up rate 2-3℃/s. Ramp-down rate 6℃/s Max. No mechanical problem found. No electrical failure found per our specification.

6.4 Vibration: 1.5mm amplitude total excursion 10-55-10 Hz traversed in 1minute, x.y.z, axis for 2 hours. Shall not be any abnormality.

6.5 Random drop (Packing condition): Height 60cm, 3 times on the wood floorboard ,shall not be any abnormality.

6.6 Dry heat: 100+/-2℃ 96 hours.

6.7 Cold: -20+/-2℃ 96 hours.

6.8 Damp Heat: 60+/-2℃, 93+/-3% RH 96 hours.

6.9 Change of temperature: exposed 5 cycle; each consisting of 30 minutes at -20+/-2℃,2-3minutes at 20+/-2℃,30 minutes at 85+/-2℃, 2-3 minutes at 20+/-2℃.